



Solid State Relay
OCMOS FET

PS7160-2A, PS7160L-2A

8-PIN DIP, 600 V BREAK DOWN VOLTAGE
NORMALLY OPEN TYPE
2-ch Optical Coupled MOS FET

–NEPOC Series–

DESCRIPTION

The PS7160-2A and PS7160L-2A are solid state relays containing GaAs LEDs on the light emitting side (input side) and MOS FETs on the output side.

They are suitable for analog signal control because of their low offset and high linearity.

The PS7160L-2A has a surface mount type lead.

FEATURES

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- 2 channel type (1 a + 1 a output)
- Low LED operating current ($I_F = 2 \text{ mA}$)
- Designed for AC/DC switching line changer
- Small package (8-pin DIP)
- Low offset voltage
- Ordering number of taping product: PS7160L-2A-E3, E4: 1 000 pcs/reel
- Pb-Free product
- Safety standards
 - UL approved: File No. E72422
 - BSI approved: No. 8245/8246
 - CSA approved: No. CA 101391

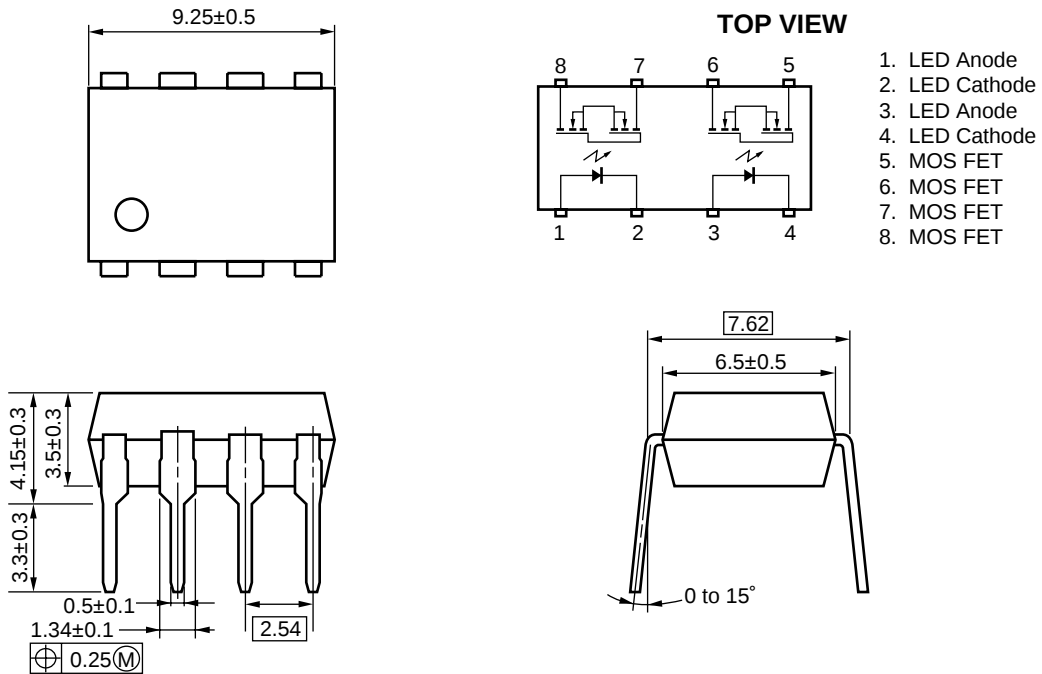
APPLICATIONS

- Exchange equipment
- Measurement equipment
- FA/OA equipment

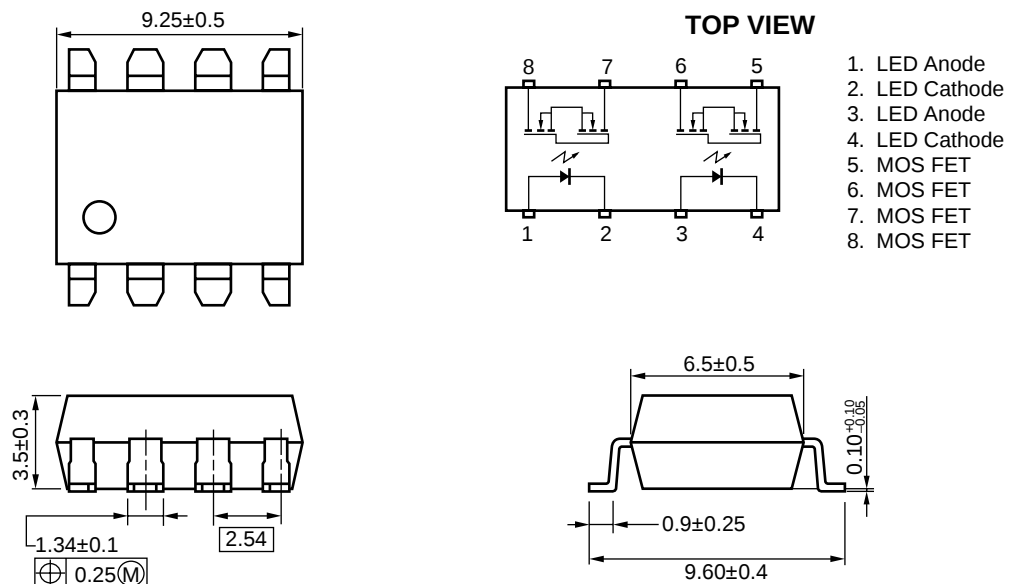
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PACKAGE DIMENSIONS (in millimeters)

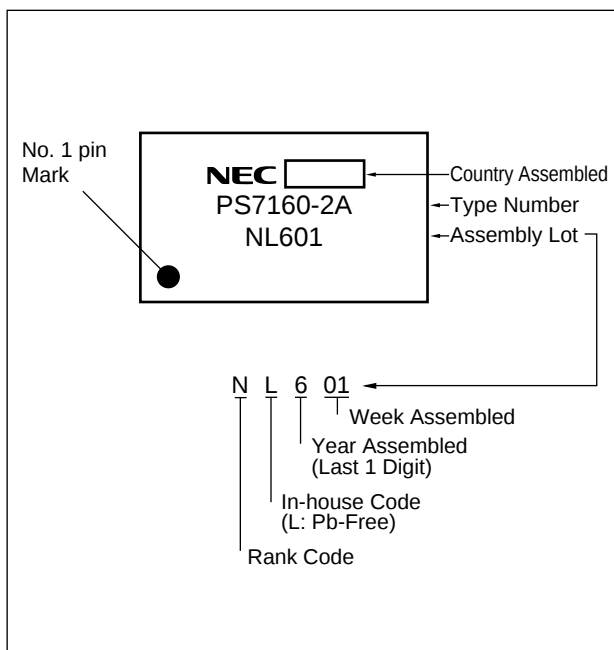
PS7160-2A



PS7160L-2A



<R> **MARKING EXAMPLE**



<R> ORDERING INFORMATION

Part Number	Order Number	Solder Plating Specification	Packing Style	Safety Standard Approval	Application Part Number ^{*1}
PS7160-2A	PS7160-2A-A	Pb-Free	Magazine case 50 pcs	Standard products (UL, BSI, CSA approved)	PS7160-2A
PS7160L-2A	PS7160L-2A-A				
PS7160L-2A-E3	PS7160L-2A-E3-A		Embossed Tape 1 000 pcs/reel		
PS7160L-2A-E4	PS7160L-2A-E4-A				

*1 For the application of the Safety Standard, following part number should be used.

ABSOLUTE MAXIMUM RATINGS (T_A = 25°C, unless otherwise specified)

Parameter		Symbol	Ratings	Unit
Diode	Forward Current (DC)	I _F	50	mA/ch
	Reverse Voltage	V _R	5.0	V
	Power Dissipation	P _D	50	mW/ch
	Peak Forward Current ^{*1}	I _{FP}	1	A/ch
MOS FET	Break Down Voltage	V _L	600	V
	Continuous Load Current ^{*2}	I _L	90 (120)	mA/ch
	Pulse Load Current ^{*2,3} (AC/DC Connection)	I _{LP}	250 (300)	mA/ch
	Power Dissipation	P _D	375	mW/ch
Isolation Voltage ^{*4}		BV	1 500	Vr.m.s.
Total Power Dissipation		P _T	850	mW
Operating Ambient Temperature		T _A	−40 to +85	°C
Storage Temperature		T _{stg}	−40 to +100	°C

*1 PW = 100 μs, Duty Cycle = 1%

*2 Conditions: I_F ≥ 5 mA. Load current () value is.

*3 PW = 100 ms, 1 shot

*4 AC voltage for 1 minute at T_A = 25°C, RH = 60% between input and output
Pins 1-4 shorted together, 5-8 shorted together.

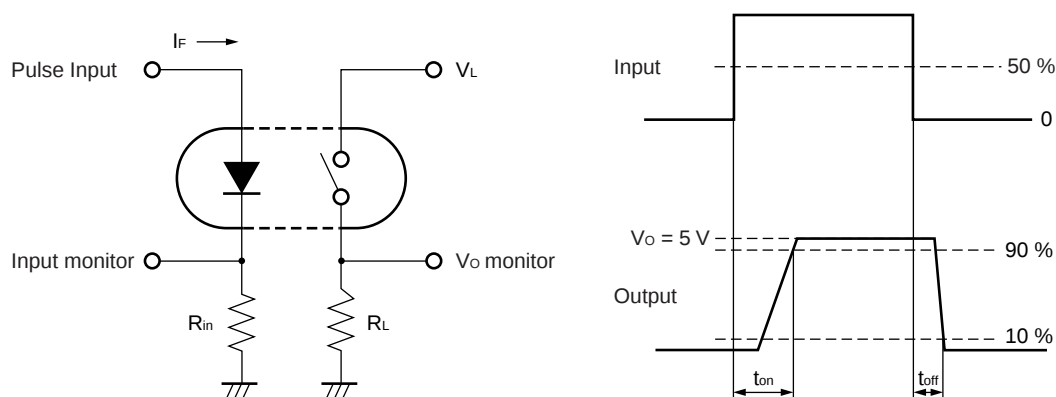
RECOMMENDED OPERATING CONDITIONS (T_A = 25°C)

Parameter	Symbol	MIN.	TYP.	MAX.	Unit
LED Operating Current	I _F	2	10	20	mA
LED Off Voltage	V _F	0		0.5	V

ELECTRICAL CHARACTERISTICS ($T_A = 25^\circ\text{C}$)

Parameter		Symbol	Conditions	MIN.	TYP.	MAX.	Unit
Diode	Forward Voltage	V_F	$I_F = 10\text{ mA}$		1.2	1.4	V
	Reverse Current	I_R	$V_R = 5\text{ V}$			5.0	μA
MOS FET	Off-state Leakage Current	I_{Leak}	$V_D = 600\text{ V}$		0.03	1.0	μA
	Output Capacitance	C_{out}	$V_D = 0\text{ V}, f = 1\text{ MHz}$		110		pF/ch
Coupled	LED On-state Current	I_{Fon}	$I_L = 90\text{ mA}$			2.0	mA
	On-state Resistance	R_{on1}	$I_F = 10\text{ mA}, I_L = 10\text{ mA}$		42	50	Ω
		R_{on2}	$I_F = 10\text{ mA}, I_L = 90\text{ mA}, t \leq 10\text{ ms}$		33	50	
	Turn-on Time ^{*1, 2}	t_{on}	$I_F = 10\text{ mA}, V_O = 5\text{ V}, R_L = 500\text{ }\Omega,$ $PW \geq 10\text{ ms}$		0.8	1.5	ms
	Turn-off Time ^{*1, 2}	t_{off}			0.06	0.2	
	Isolation Resistance	$R_{\text{I-O}}$	$V_{\text{I-O}} = 1.0\text{ kV}_{\text{DC}}$	10^9			Ω
	Isolation Capacitance	$C_{\text{I-O}}$	$V = 0\text{ V}, f = 1\text{ MHz}$		1.1		pF/ch

*1 Test Circuit for Switching Time



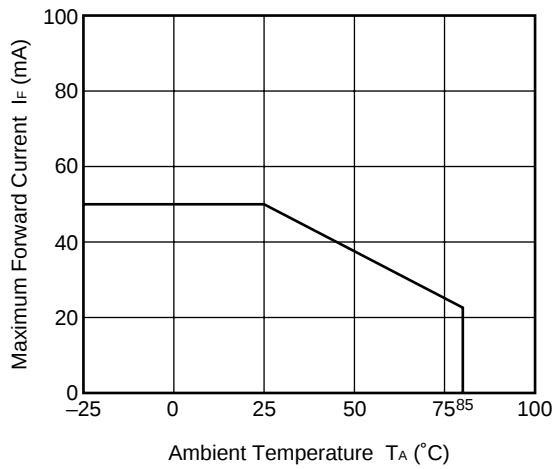
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*2 The turn-on time and turn-off time are specified as input-pulse width $\geq 10\text{ ms}$.

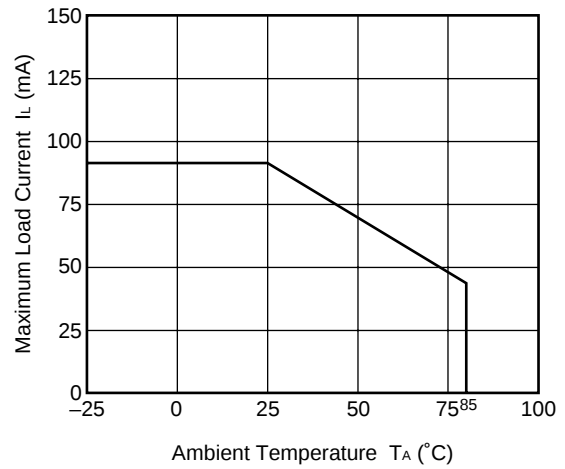
Be aware that when the device operates with an input-pulse width less than 10 ms, the turn-on time and turn-off time will increase.

TYPICAL CHARACTERISTICS ($T_A = 25^\circ\text{C}$, unless otherwise specified)

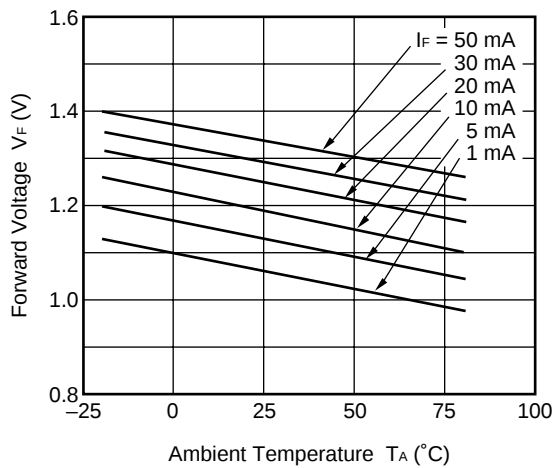
MAXIMUM FORWARD CURRENT vs. AMBIENT TEMPERATURE



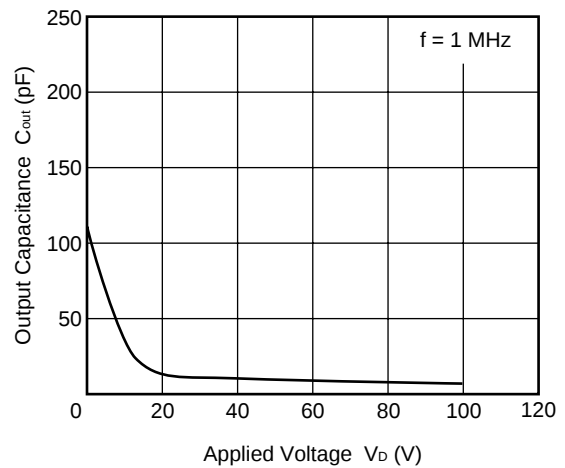
MAXIMUM LOAD CURRENT vs. AMBIENT TEMPERATURE



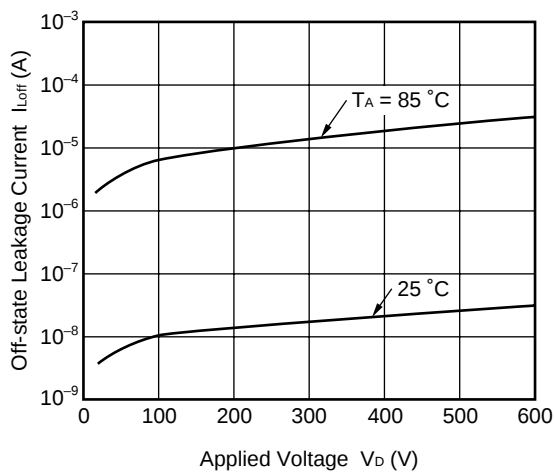
FORWARD VOLTAGE vs. AMBIENT TEMPERATURE



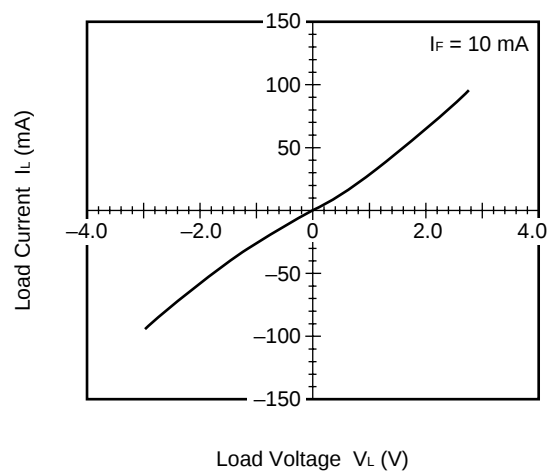
OUTPUT CAPACITANCE vs. APPLIED VOLTAGE



OFF-STATE LEAKAGE CURRENT vs. APPLIED VOLTAGE

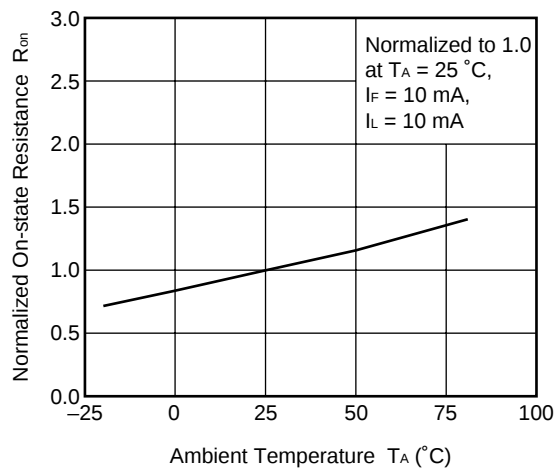


LOAD CURRENT vs. LOAD VOLTAGE

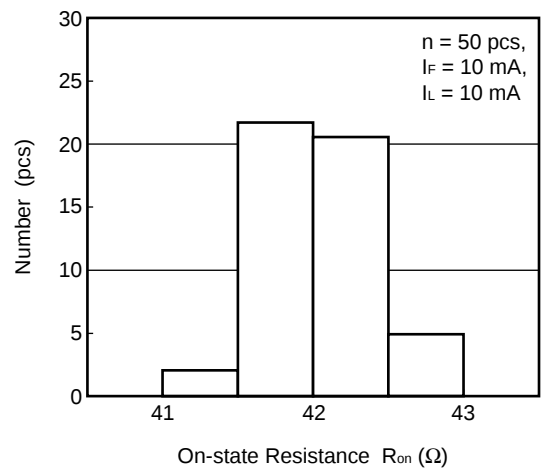


Remark The graphs indicate nominal characteristics.

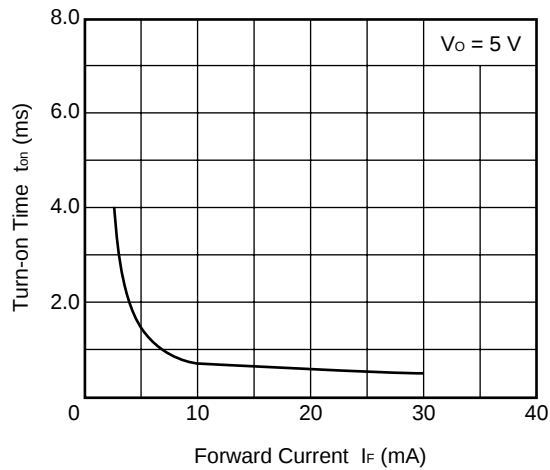
NORMALIZED ON-STATE RESISTANCE vs. AMBIENT TEMPERATURE



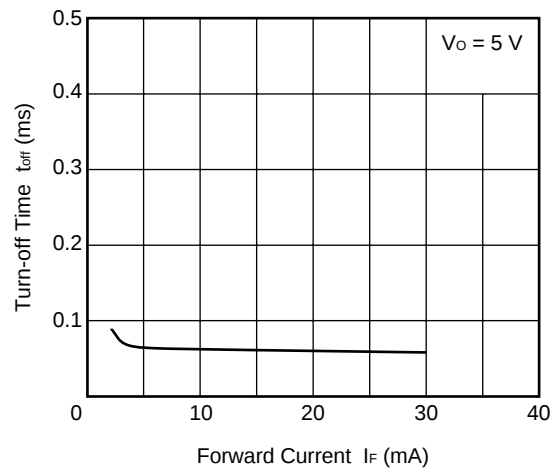
ON-STATE RESISTANCE DISTRIBUTION



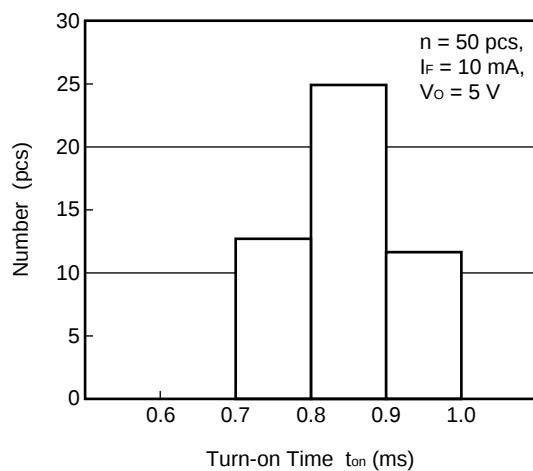
TURN-ON TIME vs. FORWARD CURRENT



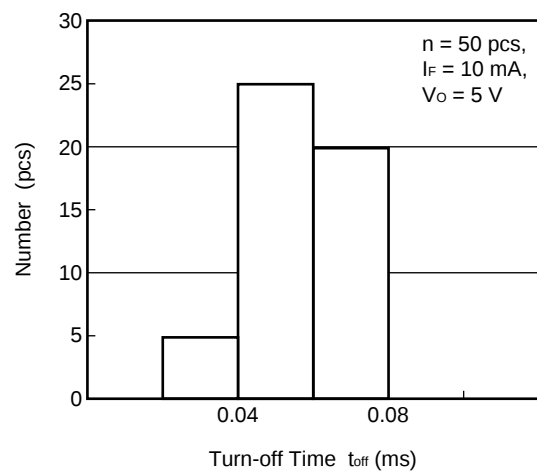
TURN-OFF TIME vs. FORWARD CURRENT



TURN-ON TIME DISTRIBUTION

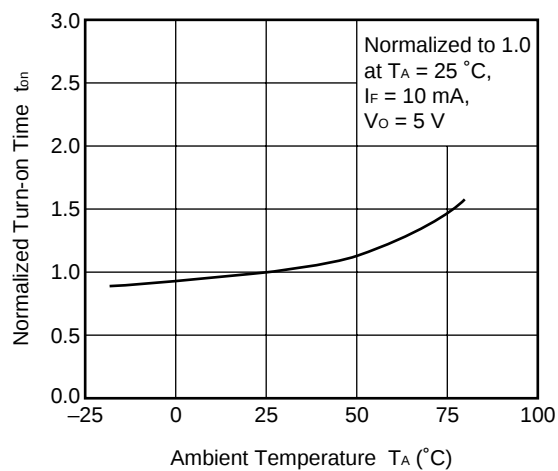


TURN-OFF TIME DISTRIBUTION

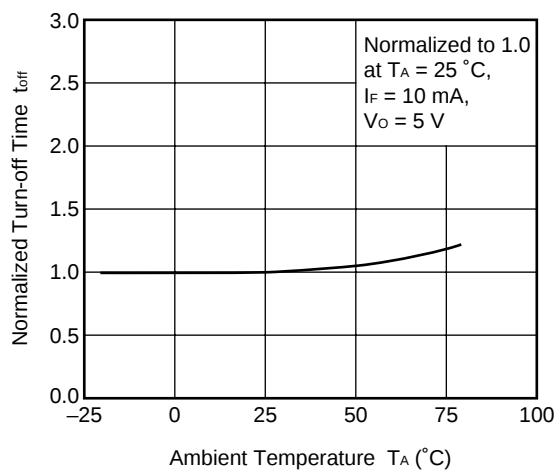


Remark The graphs indicate nominal characteristics.

**NORMALIZED TURN-ON TIME vs.
AMBIENT TEMPERATURE**

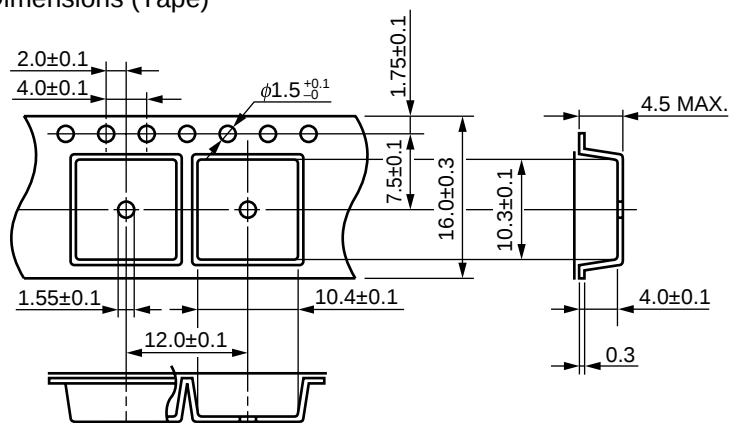


**NORMALIZED TURN-OFF TIME vs.
AMBIENT TEMPERATURE**

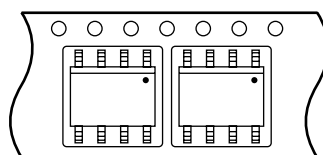


Remark The graphs indicate nominal characteristics.

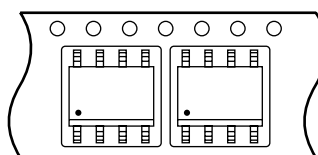
Outline and Dimensions (Tape)



PS7160L-2A-E3



PS7160L-2A-E4



Technical drawing of a circular part with a central feature. The drawing includes the following dimensions:

- Overall diameter: $\phi 21.0 \pm 0.8$
- Central feature width: 2.0 ± 0.5
- Central feature radius: $R 1.0$
- Inner dashed circle diameter: $\phi 13.0 \pm 0.2$

Technical drawing of a vertical pipe section showing dimensions for a flange. The drawing includes a side view and a cross-sectional view.

Dimensions shown:

- Overall height: $\phi 330 \pm 2.0$
- Flange thickness: 2.0 ± 0.5
- Distance from top of pipe to center of flange hole: 100 ± 1.0
- Distance from center of flange hole to outer edge of flange: 17.5 ± 1.0
- Distance from center of flange hole to outer edge of pipe: 21.5 ± 1.0
- Distance from bottom of pipe to outer edge of flange: 15.9 to 19.4

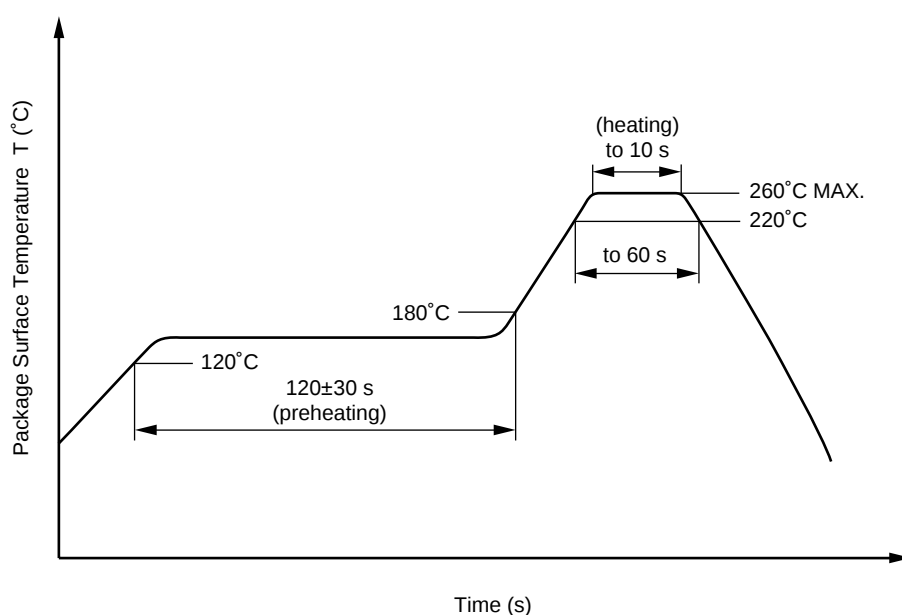
Outer edge of flange

RECOMMENDED SOLDERING CONDITIONS

(1) Infrared reflow soldering

- | | |
|---|--|
| • Peak reflow temperature | 260°C or below (package surface temperature) |
| • Time of peak reflow temperature | 10 seconds or less |
| • Time of temperature higher than 220°C | 60 seconds or less |
| • Time to preheat temperature from 120 to 180°C | 120±30 s |
| • Number of reflows | Three |
| • Flux | Rosin flux containing small amount of chlorine (The flux with a maximum chlorine content of 0.2 Wt% is recommended.) |

Recommended Temperature Profile of Infrared Reflow



(2) Wave soldering

- | | |
|-------------------------|--|
| • Temperature | 260°C or below (molten solder temperature) |
| • Time | 10 seconds or less |
| • Preheating conditions | 120°C or below (package surface temperature) |
| • Number of times | One |
| • Flux | Rosin flux containing small amount of chlorine (The flux with a maximum chlorine content of 0.2 Wt% is recommended.) |

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(3) Soldering by soldering iron

- | | |
|--|--|
| • Peak temperature (lead part temperature) | 350°C or below |
| • Time (each pins) | 3 seconds or less |
| • Flux | Rosin flux containing small amount of chlorine (The flux with a maximum chlorine content of 0.2 Wt% is recommended.) |

(a) Soldering of leads should be made at the point 1.5 to 2.0 mm from the root of the lead.

(b) Please be sure that the temperature of the package would not be heated over 100°C.

(4) Cautions

- Fluxes

Avoid removing the residual flux with freon-based and chlorine-based cleaning solvent.

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USAGE CAUTIONS

1. Protect against static electricity when handling.
2. Avoid storage at a high temperature and high humidity.

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M8E 02.11-1

Caution GaAs Products	This product uses gallium arsenide (GaAs). GaAs vapor and powder are hazardous to human health if inhaled or ingested, so please observe the following points. • Follow related laws and ordinances when disposing of the product. If there are no applicable laws and/or ordinances, dispose of the product as recommended below. 1. Commission a disposal company able to (with a license to) collect, transport and dispose of materials that contain arsenic and other such industrial waste materials. 2. Exclude the product from general industrial waste and household garbage, and ensure that the product is controlled (as industrial waste subject to special control) up until final disposal. • Do not burn, destroy, cut, crush, or chemically dissolve the product. • Do not lick the product or in any way allow it to enter the mouth.
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► For further information, please contact

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